

ABSTRACT OF THE INVENTION

The present invention discloses an apparatus having a platen; a polishing pad disposed over the platen; a slurry dispenser disposed over the polishing pad; a cathode connected electrically to the polishing pad; a wafer carrier disposed over the polishing pad; an anode connected electrically to the wafer carrier; and a power supply connected to the anode and the cathode.

The present invention further discloses a method to remove a surface layer from a wafer using a polishing pad, a slurry, and an electrical current.